



FORM PTO-1449 U.S. DEPARTMENT OF COMMERCE
(Modified) PATENT AND TRADEMARK OFFICE

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APPLICATION NO.
09/580,026

**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**

(Use Several Sheets if Necessary)

(37 CFR 1.96(d))

APPLICANT:

S. Dershem et al.

FILING DATE:

May 26, 2000

GROUP:

1712

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Page 1 of 4

U.S. PATENT DOCUMENTS

EXAMINER'S INITIAL	PATENT NUMBER	ISSUE DATE	PATENTEE	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
SMC	H424	02-02-88	Martin et al	548	522	
↑	3,403,172	09-24-68	Jordan, Jr. et al	260	404.5	
	4,110,364	08-29-78	Gaku et al	528	170	
	4,179,551	12-18-79	Jones et al	526	262	
	4,193,829	03-18-80	Kourtides et al	156	276	
	4,311,636	01-19-82	Hahn et al	260	45.8	
	4,336,311	06-22-82	Lucey	428	521	
	4,370,467	01-25-83	Gaku et al	528	322	
	4,485,218	11-27-84	Bell et al	525	257	
	4,533,975	08-06-85	Bill	361	323	
	4,540,650	09-10-85	Klug et al	430	281	
	4,578,328	03-25-86	Kray	430	18	
	4,581,461	04-08-86	Rossi et al	548	406	
	4,613,637	09-23-86	Landis et al	524	105	
	4,621,122	11-04-86	Guilbert et al	525	422	
	4,623,559	11-18-86	Hudock	427	54.1	
SMC	4,663,424	05-05-87	Stix et al	528	182	

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EXAMINER'S INITIAL	DOCUMENT NUMBER	PUBLICATION DATE	COUNTRY OR PATENT OFFICE	CLASS	SUB CLASS	TRANSLATION	
						YES	NO
SMC	0 028 994 A2	05-1981	European	H01L	23/28		
↑	0 051 165 A1	05-1982	European	H01L	23/14		
	0 357 110 A1	03-1990	European	C09D	151/00		
	0 475 655 A2	03-1992	European	C08K	9/10		
	1-152174	06-1989	Japan	C09D	5/44	Abstract	
	4-146984	05-1992	Japan	C09J	133/08	Abstract	
SMC	93/25386	12-1993	PCT	B32B	19/00		

OTHER DOCUMENTS (Including Author, Title, Date, Relevant Pages, Place of Publication)

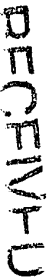
SMC		Bard and Brady, "A New Moisture Resistant Liquid Encapsulant", 42nd Electronic Components & Technology Conference, 1018-1022 (1992).
↑		Cotter et al., "The Synthesis of N-Substituted Isomaleimides", vol. 26, Jan. 1961, 10-15 (1961).
SMC		Crivello and Conlon, "Aromatic Bisvinyl Ethers: A New Class of Highly Reactive Thermosetting Monomers", Journal of Polymer Science, vol. 21, 1785-1799 (1983).

EXAMINER:

DATE CONSIDERED:

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Initial citation considered. Draw line through citation if not in conformance and not considered.
Include copy of this form with next communication to Applicant.



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Page 2 of 4

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OTHER DOCUMENTS (Including Author, Title, Date, Relevant Pages, Place of Publication)		
24C		Crivello et al., "Bismaleimide-Bisvinylether Copolymers: A New Class of Thermosetting Resins", <u>Polymer Bulletin</u> , vol. 13, 409-415 (1985).
		Hall, R. J., "Quality Assurance Specifications and Test Methods for Choosing A Solder Mask", <u>Surface Mount Int'l Conf. And Expo. Proc. Tech. Prog.</u> , 939-943 (1993).
5me		Johnson, M., "Why Use a Wet-Dry Solder Mask?", <u>Printed Circuit Fabrication</u> , vol. 13, no. 10, 74, 76, 78, 80 (1990).

DATE CONSIDERED:

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